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Fundamentals & Current Trends in Semiconductor Reliability & Quality Engineering

Course Overview

This course is aimed at those wishing to gain a basic grounding in the key elements of Integrated Circuit Reliability. As well as covering the fundamentals of Reliability Theory it also reviews recent trends arising from the challenges of continued “Moore’s Law” scaling. The correlation of Test Yield to Reliability Yield is discussed along with the most important techniques in Yield Improvement and Product Quality Management.

Topics Covered

Basic Reliability Concepts; The Bathtub Curve; Engineering Statistics; Stress-Testing and Lifetime Prediction; Knowledge-based vs. Standards-based approach; Use-Condition Models; Most Common Silicon & Package Reliability Failure Mechanisms; The Role of Failure Analysis; Upstream Reliability Design (DFR); Outlier Elimination; Case Studies.

Who Should Attend

Quality & Reliability Engineers
Product Engineers
Yield Engineers
FA Engineers
Engineering Managers

Course Duration

2 days